

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc2051hvcms8#trpbf

(Engineering Calculation)

MSOP

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**TOTAL MASS (g) : 0.0271**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001877	1000000	69261.921875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.010433	975000	384981.15625		
		Iron (Fe)	7439-89-6	0.000257	24000	9483.38574219		
		Phosphorus (P)	7723-14-0	0.000003	300	110.701004028		
		Zinc (Zn)	7440-66-6	0.000007	700	258.302337646		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.010700</b>	<b>1000000</b>	<b>394833.5625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000710	1000000	26200.15625		
		<b>External Plating Total:</b>				<b>0.000710</b>	<b>1000000</b>	<b>26200.15625</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000086	1000000	3173.4284668		
<b>Internal Plating Total:</b>				<b>0.000086</b>	<b>1000000</b>	<b>3173.4284668</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000658	750000	24280.4199219		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000219	250000	8081.17236328		
<b>Die Attach Total:</b>				<b>0.000877</b>	<b>1000000</b>	<b>32361.59375</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001659	130000	61217.6523438		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.010591	830000	390811.4375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000447	35000	16494.4492188		
		Carbon Black (C)	1333-86-4	0.000064	5000	2361.62133789		
		<b>Encapsulation Total:</b>				<b>0.012761</b>	<b>1000000</b>	<b>470885.125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000089	1000000	3284.12963867		
					<b>TOTAL MASS (g) :</b>	<b>0.0271</b>		